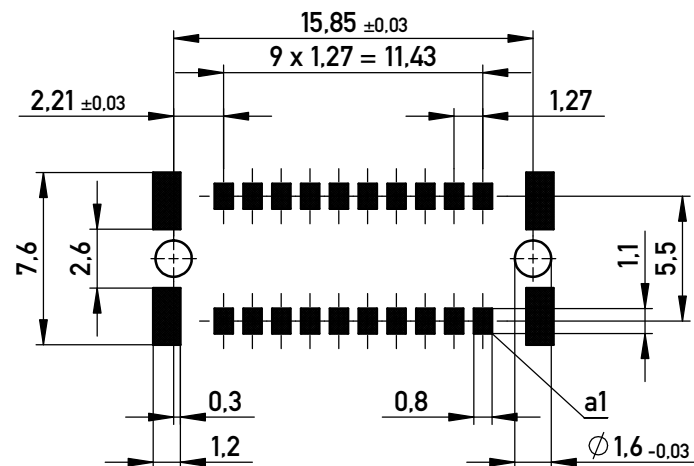


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



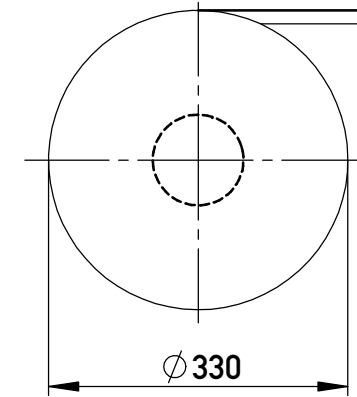
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

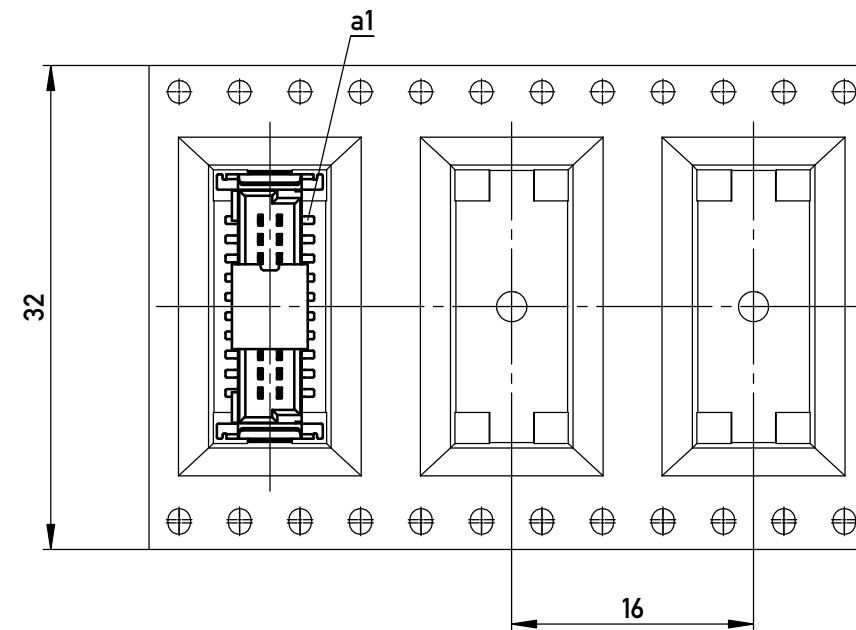
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 280 Stück
Packaging unit: 280 pcs



Abspulrichtung - *Reel off Direction*



BA 8 - 8mm Bauhöhe
type 8-13 - Low Profile

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Information:		Tolerances	All Dimensions in mm	Scale 3:1
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e		23.05.2016		www.ERNI.com
Index	Date			
		102003210089		K
		Class SMCQ		A3